503771627 04/06/2016

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JIN HYO JUNG	01/28/2016
JUNG HYUN LEE	01/28/2016
BUM SEOK KIM	01/29/2016
SEUNG HA LEE	01/28/2016
CHANG HEE KIM	01/28/2016

RECEIVING PARTY DATA

Name:	DONGBU HITEK CO., LTD.	
Street Address:	432, TEHRAN-RO, GANGNAM-GU	
City:	SEOUL	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	06194	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15091952

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	4785.15US01	
NAME OF SUBMITTER:	JENNIFER HOSKA	
SIGNATURE:	/Jennifer Hoska/	
DATE SIGNED:	04/06/2016	

Total Attachments: 2

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PATENT REEL: 038207 FRAME: 0906

ASSIGNMENT

WHEREAS, we. Jin Hyo JUNG, Gyeonggi-do, Republic of Korea, Jung Hyun LEE, Gyeonggi-do, Republic of Korea, Bum Soek KIM, Seoul, Republic of Korea, Seung Ha LEE, Daegu, Republic of Korea, and Chang Hee KIM, Busan, Republic of Korea, ("Assignors"), have invented certain new and useful improvements in HIGH VOLTAGE SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME, for which an application for Letters Patent of the United States is being made, and which may be identified in the United States Patent Office by Application No. 15/091,952 _______, filed April 6, 2016

WHEREAS. Dongbu Hitek Co., Ltd. ("Assignee"), a business entity organized and existing under the laws of the Country of Republic of Korea, and having its principal offices at 432. Teheran-ro, Gangnam-gu Scoul, 06194 Republic of Korea, is desirous of acquiring the entire right, title and interest in and to said invention, said application and in, to and under any and all Letters Patent to be obtained therefor,

NOW, THEREFORE, for and in consideration of good and valuable consideration paid by Assignee to Assignors, the receipt and sufficiency of which is hereby acknowledged by us, we have sold, assigned and transferred, and by these presents do hereby sell, assign and transfer unto the said Assignee, its successors and assigns, our entire right, title and interest in and to said invention, said application, all applications claiming priority to said application including all divisions, continuations or renewals thereof, and the Letters Patent, both foreign and domestic, that may or shall issue, therefrom including all reissues or extensions of such patents including all of our rights under the International Convention and further including the right to suc, counterclaim and recover for past, present and future infringement of the rights assigned or to be assigned, as fully and entirely as the same would have been held by the Assignors if this assignment had not been made, and we do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to the above mentioned Assignee in accordance herewith.

We hereby authorize the above mentioned Assignee, its successors and assigns, or anyone it may properly designate, to insert in this instrument the date of execution and/or filing date and application number of said application when ascertained.

We further authorize said Assignee, its successors and assigns, or anyone it may properly designate, to apply for Letters Patent, in its own name if desired, in any and all foreign countries, and additionally to claim the filing date of said United States application and/or otherwise take advantage of the provisions of the International Convention.

Upon said consideration we do hereby covenant and agree with the said Assignee, its successors and assigns, that we will not execute in writing or do any act whatsoever conflicting with these presents, and that we or our executors or administrators will at any time upon request, without further or additional consideration, but at the expense of the said Assignee, its successors and assigns, execute such additional writings and do such additional acts as said Assignee, its successors and assigns, may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original,

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Attorney Docket No. 4785.15US01

divisional, reissued or extended Letters Patent of the United States, or of any and all foreign countries on said invention, and in enforcing any rights occurring as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or

Date: $\frac{2f}{\partial l}/20/6$ Day/Month/Year

Jin Hyo JUNG

Date: 28/01/2016
Day/Month/Year

ung Hyun LEE

Date: $\frac{29/o//20/6}{\text{Day/Month/Year}}$

Date: 28/01/2016

Day/Month/Year

Soung Ha LEE

Date: \(\frac{\frac{20}{6}}{Day/Month/Year} \)